

## 1200V, 15A, Trench FS II Fast IGBT

### General Description

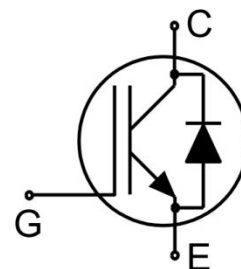
Using NCE's proprietary trench design and advanced FS (Field Stop) second generation technology, the 1200V Trench FSII IGBT offers superior conduction and switching performances, and easy parallel operation;

### Features

- Trench FSII Technology offering
- Very low  $V_{CE(sat)}$
- High speed switching
- Positive temperature coefficient in  $V_{CE(sat)}$
- Very tight parameter distribution
- High ruggedness, temperature stable behavior

### Application

- Air Condition
- Inverters
- Motor drives



Schematic diagram

### Package Marking and Ordering Information

Device	Device Package	Device Marking
NCE15TD120BD	TO-263	NCE15TD120BD



TO-263

### Absolute Maximum Ratings ( $T_C=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Units
$V_{CES}$	Collector-Emitter Voltage	1200	V
$V_{GES}$	Gate- Emitter Voltage	$\pm 30$	V
$I_C$	Collector Current	30	A
	Collector Current @ $T_C = 100^{\circ}\text{C}$	15	A
$I_{Cpuls}$	Pulsed Collector Current, $t_p$ limited by $T_{jmax}$	45	A
-	turn off safe operating area, $V_{CE}=1200\text{V}$ , $T_j=175^{\circ}\text{C}$	45	A
$I_F$	Diode Continuous Forward Current @ $T_C = 100^{\circ}\text{C}$	15	A
$I_{FM}$	Diode Maximum Forward Current	45	A
$P_D$	Power Dissipation @ $T_C = 25^{\circ}\text{C}$	300	W
	Power Dissipation @ $T_C = 100^{\circ}\text{C}$	150	W
$T_J, T_{stg}$	Operating Junction and Storage Temperature Range	-55 to +175	$^{\circ}\text{C}$
$T_L$	Maximum Temperature for Soldering	260	$^{\circ}\text{C}$
$t_{sc}$	Short circuit withstand time $V_{GE}=15.0\text{V}$ , $V_{CC} \leq 600\text{V}$ , Allowed number of short circuits<1000Time between short circuits: $\geq 1.0\text{s}$ , $T_j \leq 150^{\circ}\text{C}$	10	us

## Thermal Characteristic

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Thermal Resistance, Junction to case for IGBT	0.50	$^{\circ}\text{C/W}$
$R_{\theta JC}$	Thermal Resistance, Junction to case for Diode	0.94	$^{\circ}\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	40	$^{\circ}\text{C/W}$

## Electrical Characteristics ( $T_c=25^{\circ}\text{C}$ unless otherwise noted)

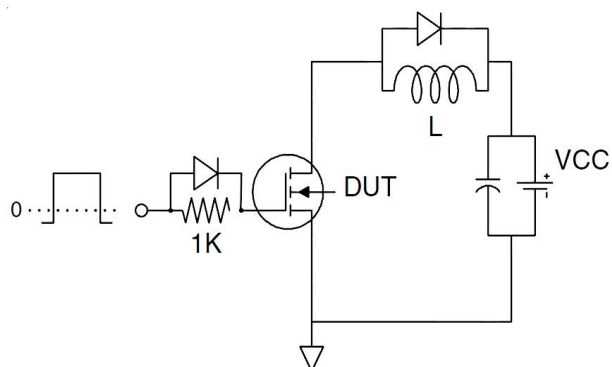
Symbol	Parameter	Conditions	Value			Units	
			Min.	Typ.	Max.		
Static Characteristics							
V <sub>(BR)CES</sub>	Collector-Emitter Breakdown Voltage	V <sub>GE</sub> =0V, I <sub>CE</sub> =1mA		1200	--	--	V
I <sub>CES</sub>	Collector-Emitter Leakage Current	V <sub>GE</sub> =0V, V <sub>CE</sub> =1200V		--	--	100	uA
I <sub>GES(F)</sub>	Gate to Emitter Forward Leakage	V <sub>GE</sub> =+30V, V <sub>CE</sub> =0V		--	--	200	nA
I <sub>GES(R)</sub>	Gate to Emitter Reverse Leakage	V <sub>GE</sub> =-30V, V <sub>CE</sub> =0V		--	--	200	nA
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	V <sub>GE</sub> =15V,	T <sub>J</sub> =25°C	--	1.55	1.80	V
		I <sub>C</sub> =15A	T <sub>J</sub> =175°C	--	1.80	--	V
V <sub>GE(th)</sub>	Gate Threshold Voltage	I <sub>C</sub> =1mA, V <sub>CE</sub> =V <sub>GE</sub>		5.0	--	6.5	V
Dynamic Characteristics							
C <sub>ies</sub>	Input Capacitance	V <sub>CE</sub> =30V, V <sub>GE</sub> =0V, f=1MHz		--	1430	--	pF
C <sub>oes</sub>	Output Capacitance			--	35	--	
C <sub>res</sub>	Reverse Transfer Capacitance			--	25	--	
Q <sub>g</sub>	Total Gate Charge	V <sub>CC</sub> =600V, I <sub>C</sub> =15A V <sub>GE</sub> =15V		--	90	--	nC
Q <sub>ge</sub>	Gate to Emitter Charge			--	11	--	nC
Q <sub>gc</sub>	Gate to Collector Charge			--	58	--	nC
I <sub>C(SC)</sub>	Short circuit collector current Max.1000 short circuits Time between short circuits: ≥1.0s	V <sub>GE</sub> =15V, V <sub>CC</sub> ≤600V, t <sub>SC</sub> ≤10us, T <sub>J</sub> ≤150°C		--	80	--	A
Switching Characteristics							
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>CE</sub> =600V, I <sub>C</sub> =15A V <sub>GE</sub> =0/15V, R <sub>g</sub> =8Ω Inductive Load		--	19	--	ns
t <sub>r</sub>	Rise Time			--	17	--	
t <sub>d(OFF)</sub>	Turn-Off Delay Time			--	170	--	
t <sub>f</sub>	Fall Time			--	18	--	
E <sub>on</sub>	Turn-On Switching Loss			--	0.9	--	mJ
E <sub>off</sub>	Turn-Off Switching Loss			--	0.6	--	
E <sub>ts</sub>	Total Switching Loss			--	1.5	--	

## Electrical Characteristics of the Diode ( $T_c=25^{\circ}\text{C}$ unless otherwise specified)

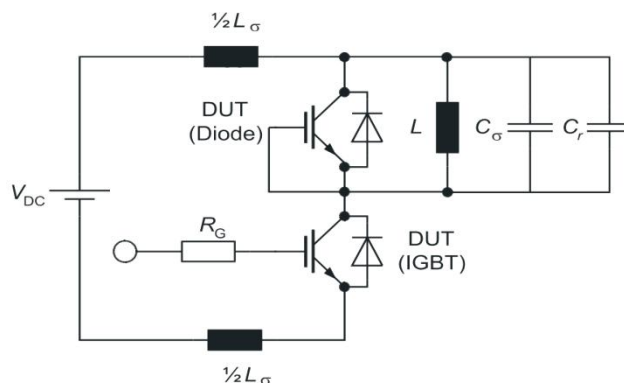
Symbol	Parameter	Conditions	Rating			Units
			Min.	Typ.	Max.	
V <sub>FM</sub>	Diode Forward Voltage	I <sub>F</sub> =15A	--	2.2	2.8	V
T <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =15A, di/dt=200A/us	--	120	--	ns
I <sub>RRM</sub>	Diode Peak Reverse Recovery Current		--	12	--	A
Q <sub>rr</sub>	Reverse Recovery Charge		--	0.72	--	uC
Pulse width t <sub>p</sub> ≤380μs,δ≤2%						

## Test Circuit

### 1) Gate Charge Test Circuit

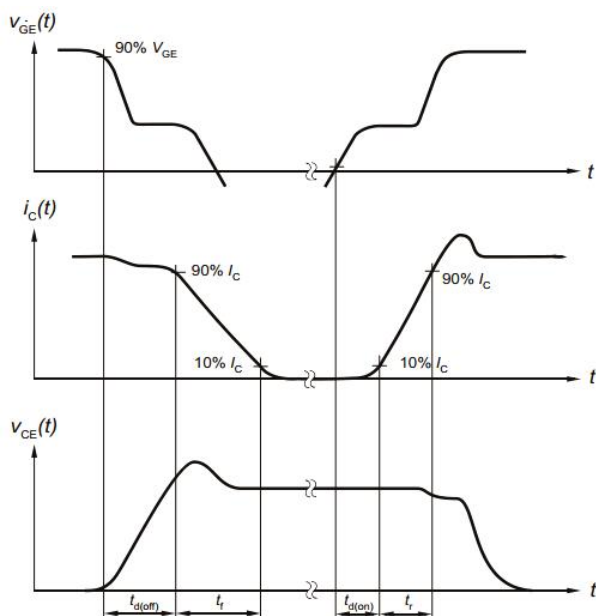


### 2) Switch Time Test Circuit

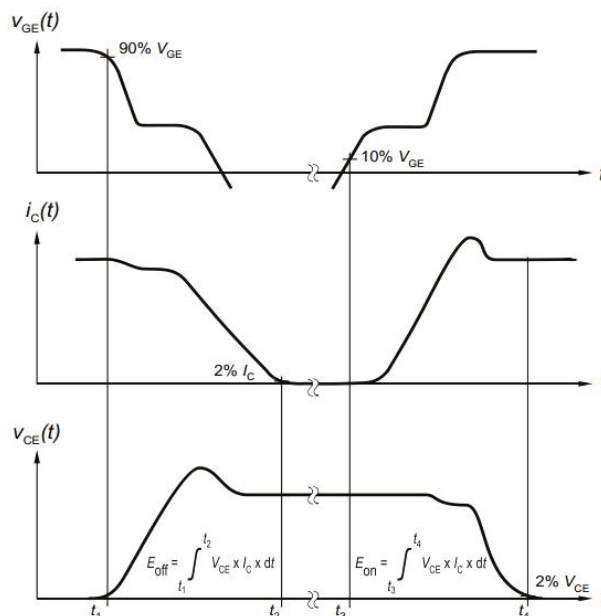


## Switching characteristics

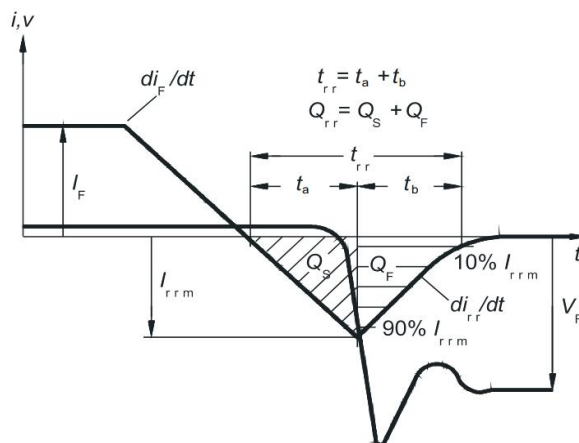
### 1) Definition of switching times



### 2) Definition of switching losses



### 3) Definition of diode switching characteristics



## Typical Electrical and Thermal Characteristics

Figure 1 Output Characteristics

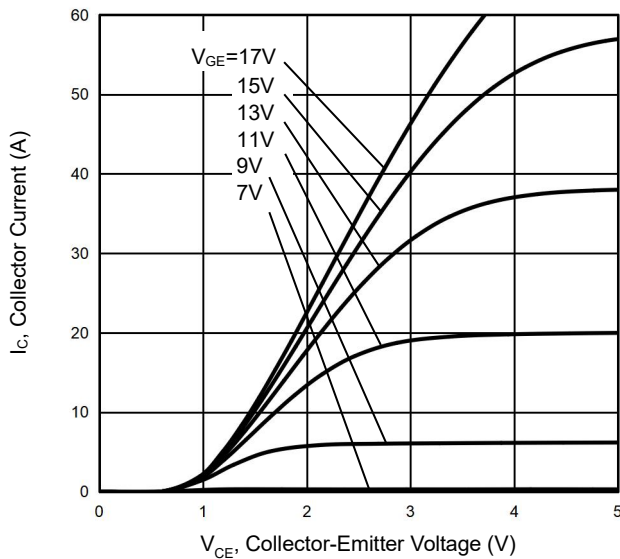


Figure 2 Transfer Characteristics

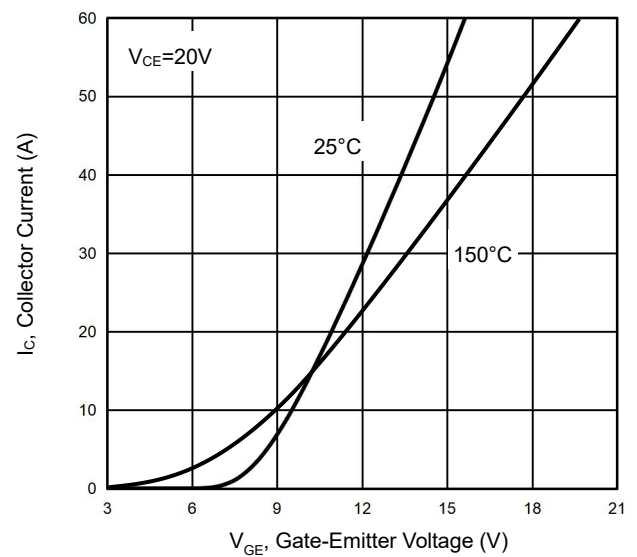


Figure 3  $V_{CE(sat)}$  vs. Case Temperature

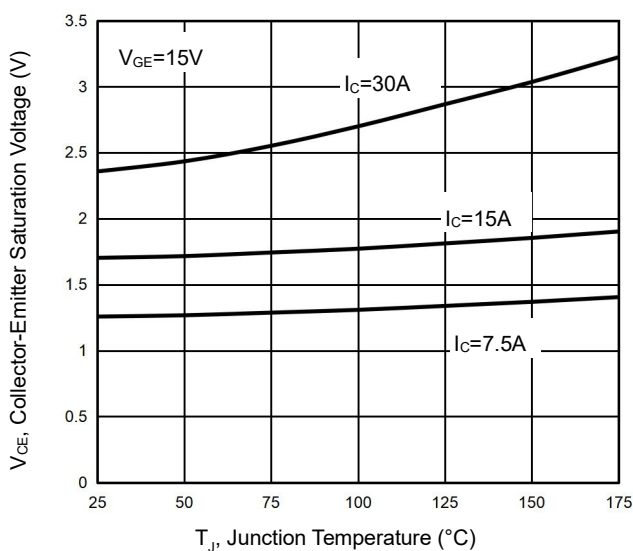


Figure 4 Saturation Voltage vs.  $V_{GE}$

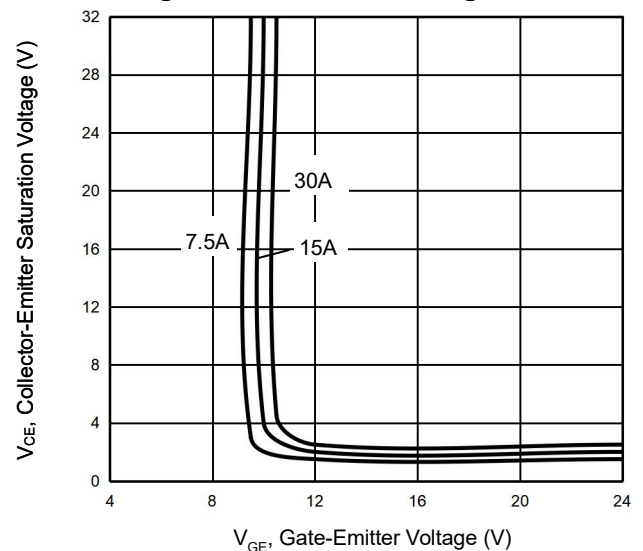


Figure 5 Capacitance Characteristics

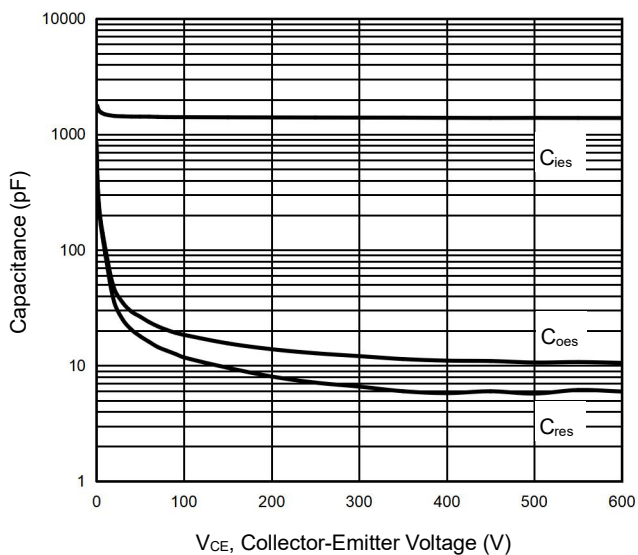
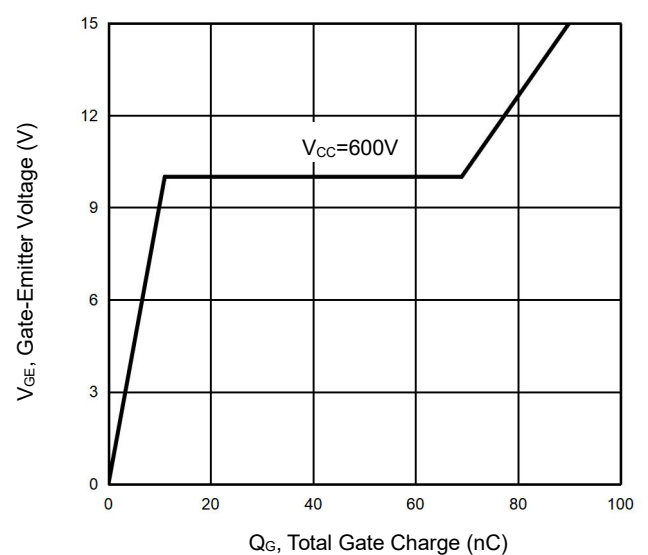


Figure 6 Gate Charge Wave Form



## Typical Electrical and Thermal Characteristics

Figure 7 Forward Characteristics

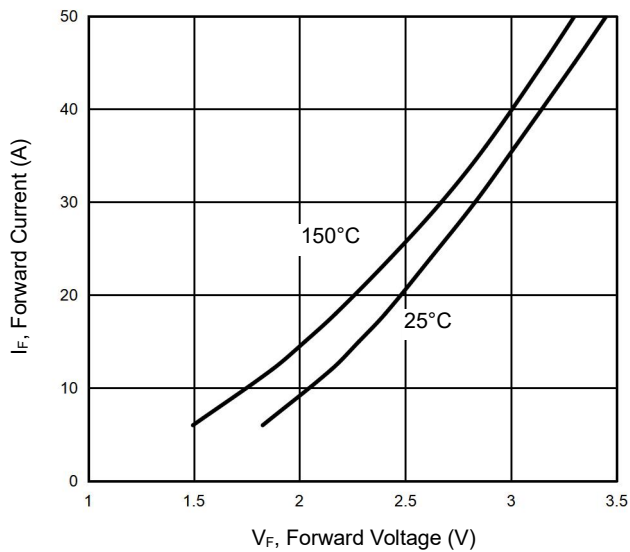


Figure 8  $V_F$  vs. Temperature

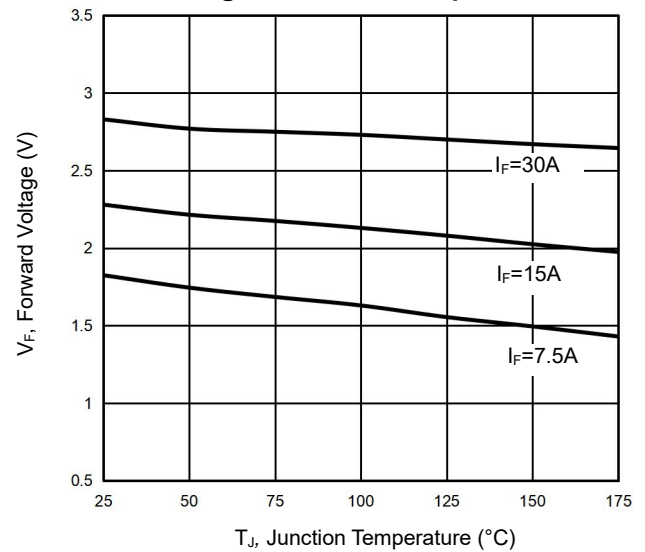


Figure 9 Switching Energy vs. Temperature

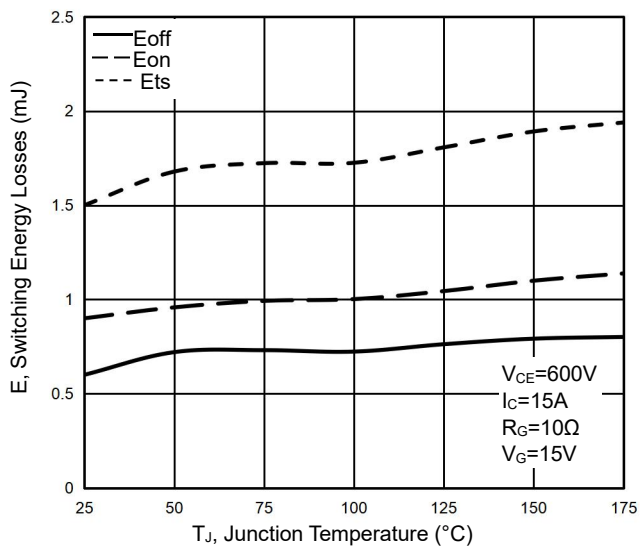


Figure 10 Forward Bias Safe Operating Area

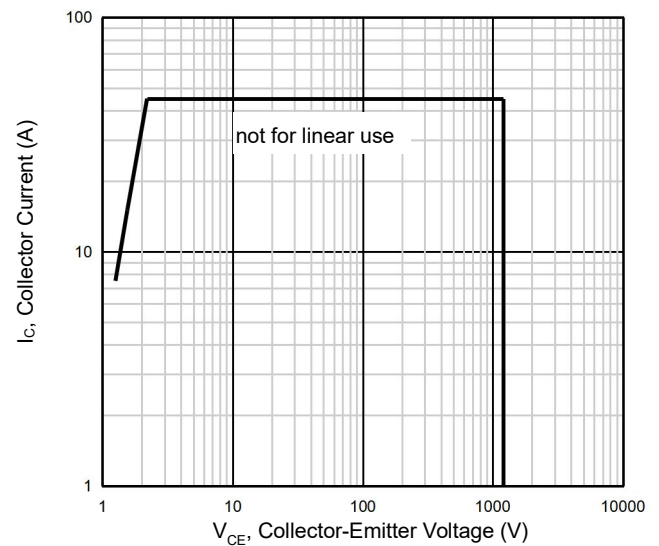


Figure 11 Gate-Emitter Threshold Voltage as a Function of Junction Temperature

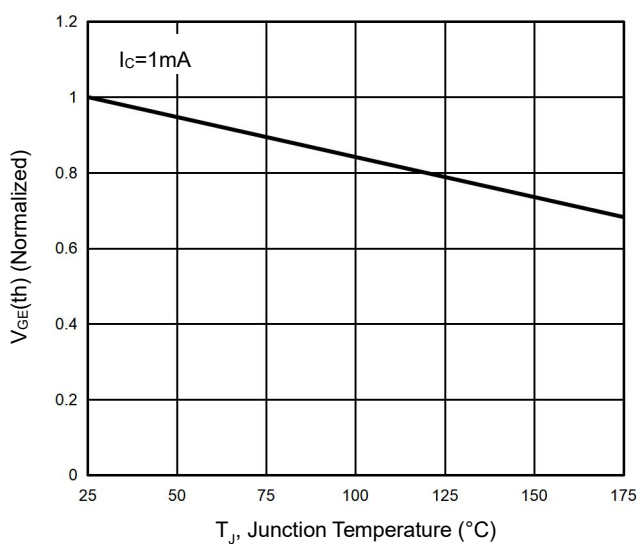
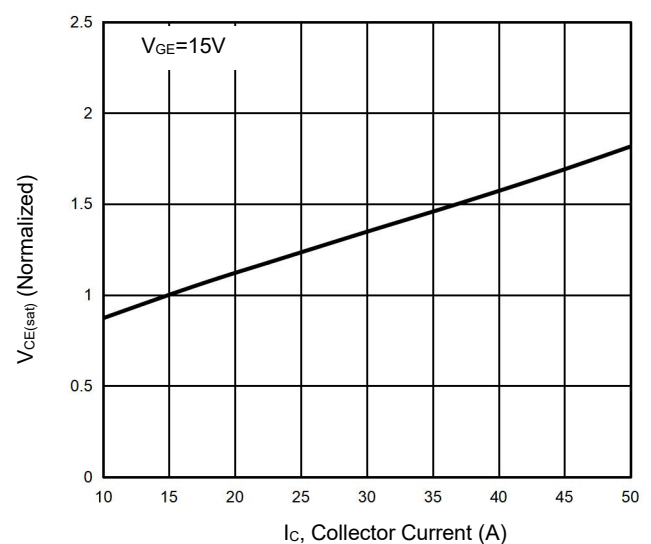


Figure 12 Typical Collector-Emitter Saturation Voltage as a function of Collector Current



## Typical Electrical and Thermal Characteristics

Figure 13 IGBT Transient Thermal Impedance

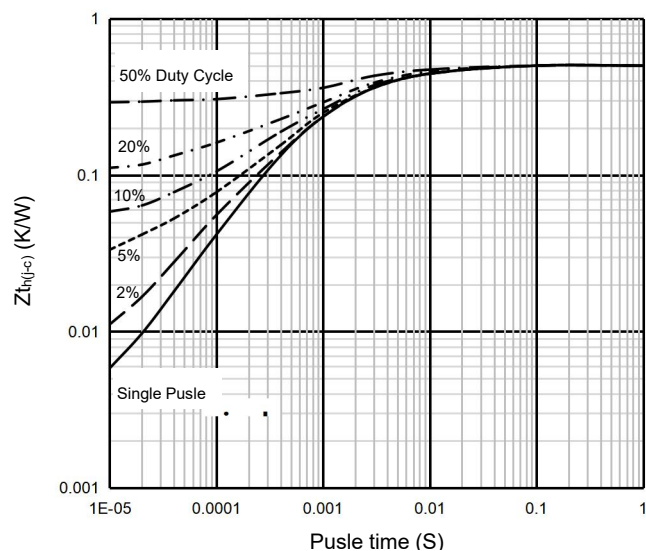
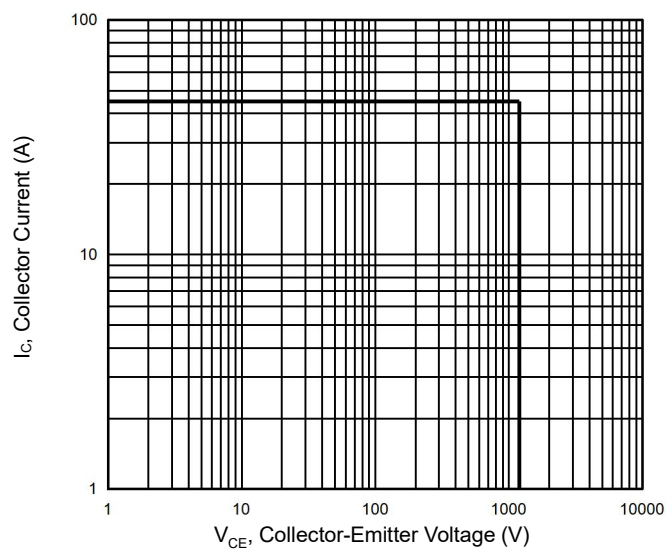
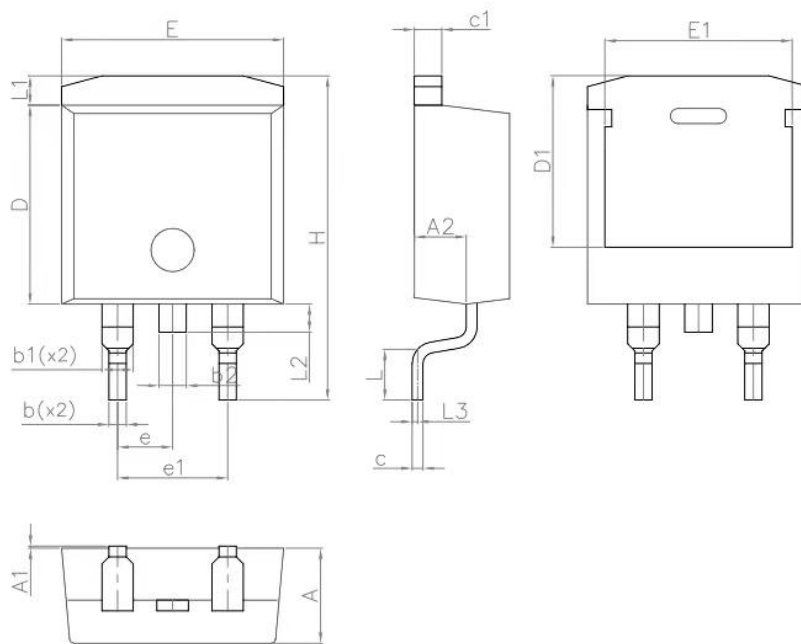


Figure 14 Reverse Bias SOA



## TO-263-E Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.20	4.60	0.17	0.18
A1	0.00	0.25	0.00	0.01
A2	2.20	2.60	0.09	0.10
b	0.70	0.90	0.03	0.04
b1	1.20	1.75	0.05	0.07
b2	1.17	1.37	0.05	0.06
c	0.40	0.60	0.02	0.03
c1	1.15	1.40	0.05	0.06
D	9.10	9.30	0.36	0.37
D1	7.63	8.23	0.30	0.32
E	10.05	10.45	0.40	0.41
E1	8.35	8.95	0.33	0.35
e	2.54 BSC		0.10 BSC	
e1	5.08 BSC		0.20 BSC	
H	14.61	15.88	0.58	0.63
L	1.78	2.79	0.07	0.11
L1	1.36 REF			
L2	1.30 REF			
L3	0.25 REF			

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